

Parker Chomerics CHO-BOND 1024 Conductive Silicone Splicing Compound

Category : Polymer , Adhesive , Thermoset

Material Notes:

Conductive splicing compounds are intended for making "custom" EMI/RFI gaskets from standard CHO-SEAL® and CHO-SIL® strips. Compounds consist of Chomerics silver-bearing powders dispersed in silicone binder. Applications: THERMATTACH have been designed to provide a high performance bond in the assembly of EBGA and TBGA semiconductor packages. Their thermally conductive filler ensures superior package performance when used to bond the flex or laminate substrate to stiffeners and heat spreaders. Information provided by Chomerics

Order this product through the following link:

http://www.lookpolymers.com/polymer_Parker-Chomerics-CHO-BOND-1024-Conductive-Silicone-Splicing-Compound.php

Physical Properties	Metric	English	Comments
Density	3.20 g/cc	0.116 lb/in ³	
Solubility in Water	0.00 %	0.00 %	Insoluble

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	125 °C	257 °F	
Minimum Service Temperature, Air	-55.0 °C	-67.0 °F	

Processing Properties	Metric	English	Comments
Pot Life	30 min	30 min	
	@Temperature 24.0 °C	@Temperature 75.2 °F	
Shelf Life	20160 min	20160 min	
	@Temperature -35.0 °C	@Temperature -31.0 °F	
Shelf Life	6.00 Month	6.00 Month	Parts A & B

Descriptive Properties	Value	Comments
Part A/B/C %	23/3.5/73.5	

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